

IN THE CLAIMS

1. (Currently Amended) A wiring board comprising:

a substrate in which a build-up layer is formed by laminating an insulating layer and a wiring layer in alternate fashion;

an opening formed so as to penetrate said build-up layer;

an electronic component; and

an embedding resin having a dielectric constant of less than or equal to about 5 and $\tan\delta$ of less than or equal to about 0.08; and

a substrate in which a build-up layer formed by laminating an insulating layer and a wiring layer in alternate fashion is formed on said embedding resin;

wherein, said electronic component is embedded in said opening by said embedding resin.

2. (Original) The wiring board according to claim 1, wherein said embedding resin comprises carbon black in an amount of less than or equal to about 1.4 mass%.

3. (Original) The wiring board according to claim 1, wherein said embedding resin comprises a thermosetting resin as a resin component and at least one inorganic filler.

4. (Original) The wiring board according to claim 3, wherein said thermosetting resin is at least one of a bisphenol-type epoxy resin, a naphthalene-type epoxy resin, a phenol-novolak-type epoxy resin, or a cresol-novolak-type epoxy resin.

5. (Original) The wiring board according to claim 1, wherein said embedding resin assumes a color having a base color tone of black, blue, green, red, orange, yellow, or violet.

6. (Canceled without prejudice or disclaimer)

7. (Canceled without prejudice or disclaimer)
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